

ABSTRACT OF THE DISCLOSURE

In a chip-stack semiconductor device including multiple semiconductor chips vertically stacked on top of each other, each of the semiconductor chips includes multiple through electrodes connected to each other in regions inside of electrode pads derived from a device region, and each of the through electrodes links a front surface to a back surface of the semiconductor chip. This arrangement provides a chip-stack semiconductor device which can prevent the increase in the size of the device and resolve the difficulty of stacking multiple semiconductor chips on top of each other, both of which are the problems associated with the provision of a number of through electrodes.